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CHINLINK INTERNATIONAL HOLDINGS LIMITED

普匯中金國際控股有限公司*

(Incorporated in Bermuda with limited liability)

(Stock Code: 0997)

**ISSUE OF FOURTH TRANCHE OF BONDS DUE 2020
AND COMPLETION OF ISSUE OF BONDS**

Placing Agent



英皇證券(香港)有限公司
Emperor Securities Limited

Reference is made to the announcements of Chinlink International Holdings Limited (the “**Company**”) dated 30 July 2019, 8 August 2019 and 19 August 2019 (collectively, the “**Announcements**”) in relation to the placing of the Bonds and the respective issue of the first, second and third tranches of Bonds. Unless otherwise defined, capitalised terms used herein shall have the same meanings as those defined in the Announcements.

The Board is pleased to announce that the fourth tranche of Bonds in principal amount of HK\$32 million (the “**Fourth Tranche Bonds**”) was issued on 6 September 2019 pursuant to the terms and conditions of the Placing Agreement. The Fourth Tranche Bonds will mature on the first anniversary of the date of issue.

* For identification purpose only

As at the date of this announcement, the Bonds in an aggregate principal amount of HK\$200 million, being the entire amount of the Bonds, have been fully placed and issued to the Placees pursuant to the Placing Agreement.

By order of the Board
Chinlink International Holdings Limited
Mr. Li Weibin
Chairman

Hong Kong, 6 September 2019

As at the date of this announcement, the Board comprises three executive Directors, namely Mr. Li Weibin, Mr. Siu Wai Yip and Mr. Lau Chi Kit; a non-executive Director, namely Ms. Fung Sau Mui; and three independent non-executive Directors, namely Dr. Ho Chung Tai, Raymond, Ms. Lai Ka Fung, May and Ms. Chan Sim Ling, Irene.